ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES international and Pan-American co	ourn, Illinois, All rights reserved	under both Iev	nis docume vel parts, th	nt is a declaration ne declaration en	on of the sub acompasses a	stances w all lower l	vithin the manufactur level materials for wl	er listed ite hich the ma	m. Note: if t nufacturer h	he item is an as as engineering	sembly with lower responsibility.	
IPC Web Site for Information on I   http://www.ipc.org/IPC-175x	21.1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material				als and Mfg Information				
Supplier Information												
ompany name* Company unique ID			Unique ID Authority				Response Date*					
onsemi	i								2023-06-08			
Contact Name	Title - Contact		P	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance		I	NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards		NA				Product-Env-Stewards@onsemi.com						
Requester Item Number Mfr Item	Number Mfr Item Name	Mfr Item Name		Effective Date	Version	Ma	Manufacturing Site		'eight*	UOM	Unit Type	
MC74VI	HCU04DR2G LOG CMOS INVERTER HEX			2023-06-08		PH	PH1		22.05	mg	Each	
Manufacturing Proccess Information								·		·	·	
Terminal Plating / Grid Array Material	erminal Base Alloy	J-STD-020 MSL R	ating	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed CU Alloy 1				260 C 30 seconds 3								
Comments												
evel 1 - maximum time at peak temperature during so	dering is 10-30 seconds											
For more information regarding material composition	please refer to page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg	
Die Attach	4.44	mg	Supplier	Silver (Ag)	7440-22-4		3.33	mg	
			Supplier	Epoxy resins	129915-35-1		1.11	mg	
Lead Frame 69.	69.62	mg	Supplier	Silver (Ag)	7440-22-4		0.7658	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.1392	mg	
			Supplier	Iron (Fe)	7439-89-6		1.8101	mg	
			Supplier	Copper (Cu)	7440-50-8		66.9048	mg	
Mold Compound-Black	43.43	mg		Epoxy Phenol Resin	proprietary data		4.5601	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		38.8699	mg	
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg	
Wire Bond - Au	0.31	mg	Supplier	Gold (Au)	7440-57-5		0.31	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted)